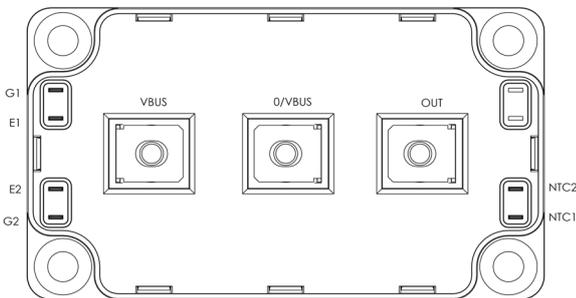
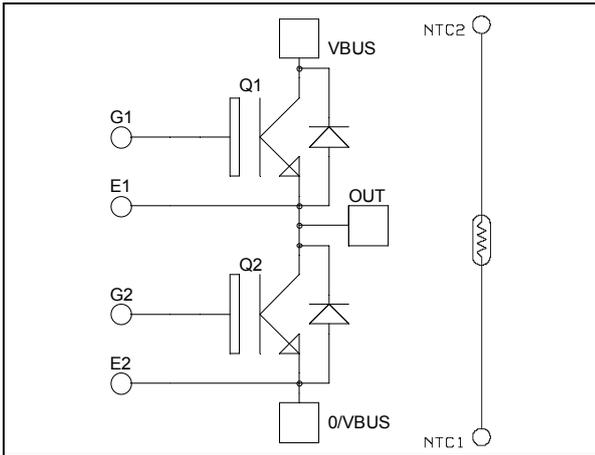


Phase leg
High speed Trench + Field Stop IGBT4
Power module

$V_{CES} = 1200V$
 $I_C = 400A @ T_c = 80^\circ C$


Application

- Welding converters
- Switched Mode Power Supplies
- Uninterruptible Power Supplies
- Motor control

Features

- High speed Trench + Field Stop IGBT 4 Technology
 - Low voltage drop
 - Low leakage current
 - Low switching losses
 - Soft recovery parallel diodes
 - Low diode VF
 - RBSOA and SCSOA rated

- Kelvin source for easy drive
- Very low stray inductance
- M5 power connectors
- High level of integration
- Internal thermistor for temperature monitoring

Benefits

- Stable temperature behavior
- Very rugged
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Easy paralleling due to positive TC of VCEsat
- Low profile
- RoHS Compliant

All ratings @ $T_j = 25^\circ C$ unless otherwise specified

Absolute maximum ratings (per IGBT)

| Symbol | Parameter | Max ratings | Unit |
|-----------|----------------------------------|---------------------|--------------|
| V_{CES} | Collector - Emitter Voltage | 1200 | V |
| I_C | Continuous Collector Current | $T_c = 25^\circ C$ | 625 |
| | | $T_c = 80^\circ C$ | 400 |
| I_{CM} | Pulsed Collector Current | $T_c = 25^\circ C$ | 1250 |
| V_{GE} | Gate - Emitter Voltage | ± 20 | V |
| P_D | Maximum Power Dissipation | $T_c = 25^\circ C$ | 1900 |
| RBSOA | Reverse Bias Safe Operating Area | $T_j = 125^\circ C$ | 800A @ 1100V |

 **CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

Electrical Characteristics (per IGBT)

| Symbol | Characteristic | Test Conditions | Min | Typ | Max | Unit |
|---------------|--------------------------------------|--------------------------------|-----|-------------|-----|---------|
| I_{CES} | Zero Gate Voltage Collector Current | $V_{GE} = 0V, V_{CE} = 1200V$ | | | 200 | μA |
| $V_{CE(sat)}$ | Collector Emitter saturation Voltage | $V_{GE} = 15V$ $I_C = 400A$ | | 2.05 2.6 | 2.4 | V |
| | | | | | | |
| $V_{GE(th)}$ | Gate Threshold Voltage | $V_{GE} = V_{CE}, I_C = 14 mA$ | 5.2 | 5.8 | 6.4 | V |
| I_{GES} | Gate – Emitter Leakage Current | $V_{GE} = 20V, V_{CE} = 0V$ | | | 680 | nA |

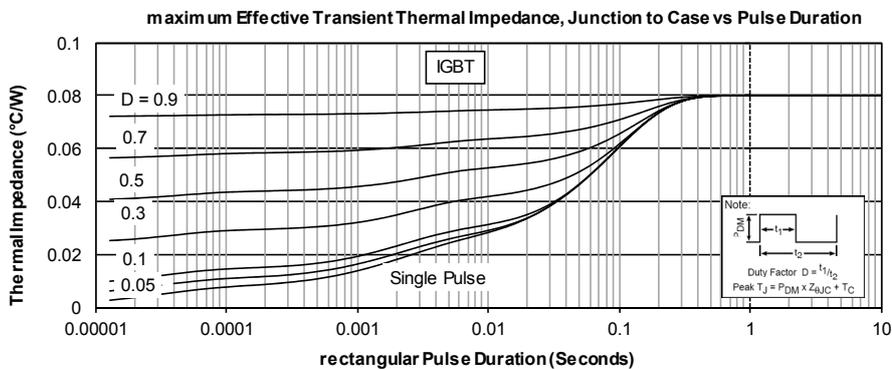
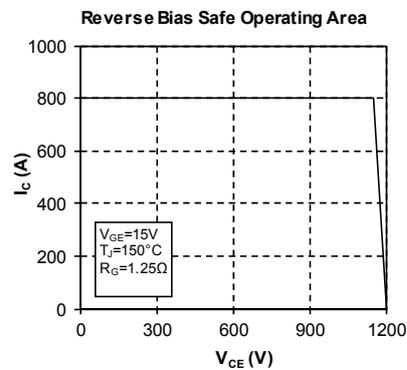
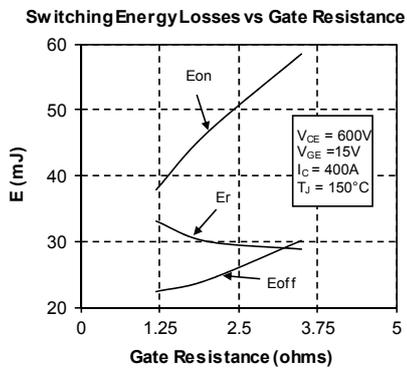
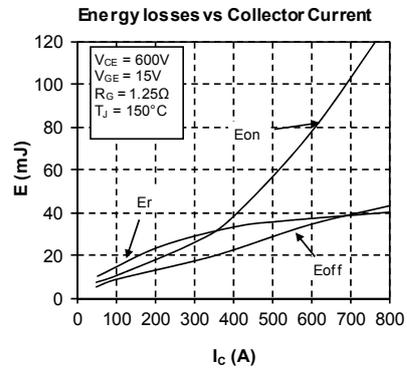
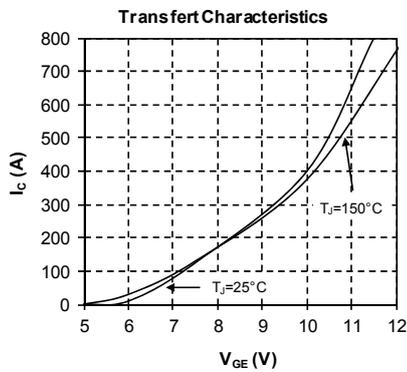
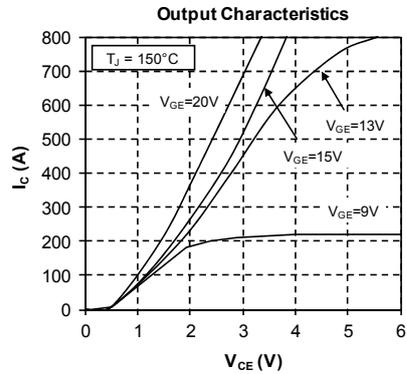
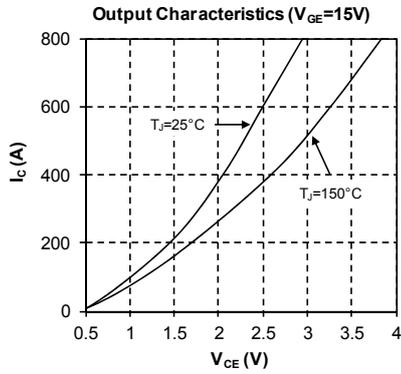
Dynamic Characteristics (per IGBT)

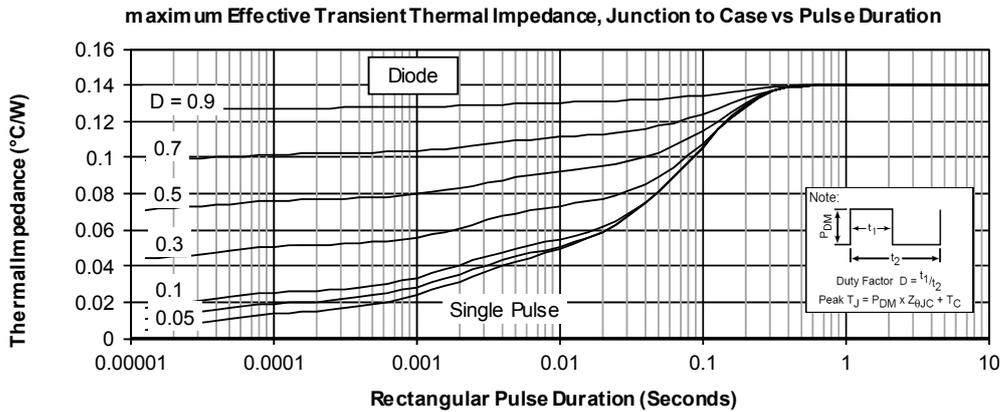
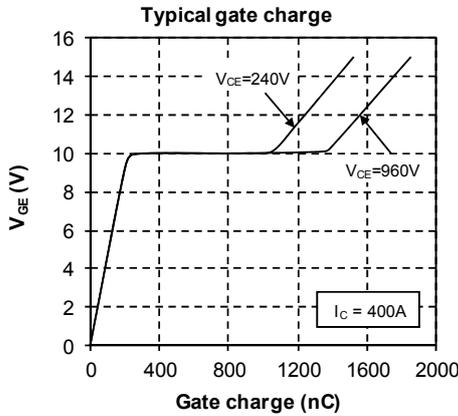
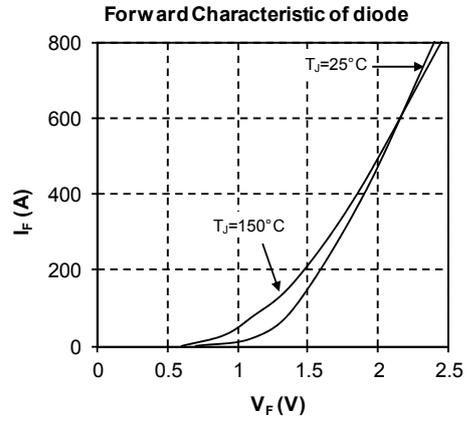
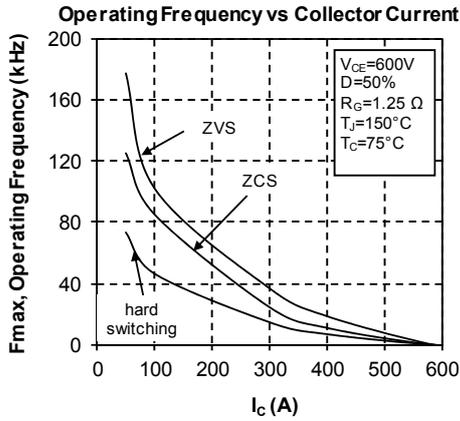
| Symbol | Characteristic | Test Conditions | Min | Typ | Max | Unit |
|--------------|-------------------------------------|--|---------------------|------|------|--------------|
| C_{ies} | Input Capacitance | $V_{GE} = 0V$ | | 24.6 | | nF |
| C_{oes} | Output Capacitance | $V_{CE} = 25V$ | | 1.4 | | |
| C_{res} | Reverse Transfer Capacitance | $f = 1MHz$ | | 1.2 | | |
| Q_G | Gate charge | $V_{GE} = 15V ; V_{CE} = 960V$ $I_C = 400A$ | | 1800 | | nC |
| $T_{d(on)}$ | Turn-on Delay Time | Inductive Switching (25°C) $V_{GE} = \pm 15V$ $V_{CE} = 600V$ $I_C = 400A$ $R_G = 1.25\Omega$ | | 30 | | ns |
| T_r | Rise Time | | | 57 | | |
| $T_{d(off)}$ | Turn-off Delay Time | | | 290 | | |
| T_f | Fall Time | | | 16 | | |
| $T_{d(on)}$ | Turn-on Delay Time | Inductive Switching (150°C) $V_{GE} = \pm 15V$ $V_{CE} = 600V$ $I_C = 400A$ $R_G = 1.25\Omega$ | | 30 | | ns |
| T_r | Rise Time | | | 49 | | |
| $T_{d(off)}$ | Turn-off Delay Time | | | 366 | | |
| T_f | Fall Time | | | 48 | | |
| E_{on} | Turn-on Switching Energy | $V_{GE} = \pm 15V$ $V_{CE} = 600V$ $I_C = 400A$ $R_G = 1.25\Omega$ | $T_j = 150^\circ C$ | 36 | | mJ |
| E_{off} | Turn-off Switching Energy | | $T_j = 150^\circ C$ | 22 | | mJ |
| I_{sc} | Short Circuit data | $V_{GE} \leq 15V ; V_{Bus} = 600V$ $t_p \leq 10\mu s ; T_j = 150^\circ C$ | | 1400 | | A |
| R_{thJC} | Junction to Case Thermal Resistance | | | | 0.08 | $^\circ C/W$ |

Diode ratings and characteristics (per diode)

| Symbol | Characteristic | Test Conditions | Min | Typ | Max | Unit | |
|------------|-------------------------------------|---|---|-------------|------|---------|---------|
| V_{RRM} | Repetitive Reverse Voltage | | | | 1200 | V | |
| I_{RM} | Reverse Leakage Current | $V_R = 1200V$ | | | 250 | μA | |
| I_F | DC Forward Current | | $T_C = 50^\circ C$ | 400 | | A | |
| V_F | Diode Forward Voltage | $I_F = 400A$ $V_{GE} = 0V$ | $T_j = 25^\circ C$ $T_j = 150^\circ C$ | 1.9 1.85 | 2.2 | V | |
| t_{rr} | Reverse Recovery Time | $I_F = 400A$ $V_R = 600V$ $di/dt = 7000A/\mu s$ | $T_j = 25^\circ C$ $T_j = 150^\circ C$ | 155 300 | | ns | |
| Q_{rr} | Reverse Recovery Charge | | $T_j = 25^\circ C$ $T_j = 150^\circ C$ | 37.2 78 | | | μC |
| E_r | Reverse Recovery Energy | | $T_j = 25^\circ C$ $T_j = 150^\circ C$ | 16 32 | | mJ | |
| R_{thJC} | Junction to Case Thermal Resistance | | | | | | 0.14 |

Typical Performance Curve





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